Announcement

INTERNATIONAL SOCIETY FOR HYBRID MICROELECTRONICS

The International Society for Hybrid Microelectronics is based in the U.S.A., and there are independent parallel organisations throughout the world. These groups are independent, non-profitmaking organisations, the purpose of which is to provide an informal means of discussing and advancing hybrid technology. This is achieved by the organisation of meetings, the publication of a Newsletter and other activities as appropriate. Membership is open to all and there are no formal entry requirements.

All these societies run a programme of meetings throughout the year on subjects concerned with thick films, and interested readers are advised to contact the following Chairmen for details of meetings in their own areas:

1. Benelux

Mr G. K. Steenvoorden Technische Hogeschool Delft Lorentzweg 1 NL.2628 C. J. DELFT Nederland

2. France

Dr B. Dreyfus-Alain President de I.F.M.H. 114 Rue de Damiette 91190 GIF SUR YVETTE, France

3. Germany

Herr W. Funk Chairman I.S.H.M. Deutschland Reinekestrasse 22 8000 MÜNCHEN 90 W. Germany

4. Italy

Dr D. Roggia, Telettra Via Trento 30 20059 VIMERCATE Italy

5. Japan

Dr A. Ikegami Hitachi Ltd., 292 Yoshida-Cho Totsuka-ku, YOKOHAMA, Japan.

6. Nordic

Mr E. Järvinen Technical Research Centre of Finland Electronics Laboratory POB 181 SF. 90101 OULU Finland

7. U.K.

Dr J. T. Law
Bio-engineering Unit
Princess Margaret Rose Hospital
Fairmile Head
EDINBURGH
Scotland
Great Britain

8. U.S.A. – all U.S. Chapters

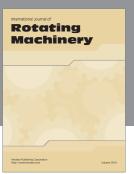
I.S.H.M.
P.O. Box 3255
MONTGOMERY
Alabama 36109, U.S.A.

In addition, the European Chapters are all linked together through the European Liaison Committee, Chairman:

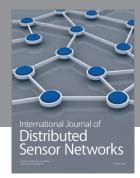
Prof. R. Govaerts, Instituut Elektrotechniek, K. U. Leuven, Kardinal Mercierlaan 94, B-3030 HEVERLEE, Belgium.

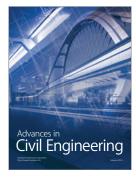
















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